



<b>Session Title:</b>	<b>[WeE1] Advanced Etching I</b>
<b>Session Date:</b>	<b>November 13 (Wed.), 2024</b>
<b>Session Time:</b>	<b>09:00-10:20</b>
<b>Session Room:</b>	<b>Room E (Sicily Room, 1F, Paradise Hotel Busan)</b>
<b>Session Chair:</b>	<b>Dr. Peter Ventzek (Tokyo Electron America Inc., USA)</b>

**[WeE1-1] [Invited]** **09:00-09:30**

### Challenges and Approaches in Advanced Patterning for Microelectronics

Chanmin Lee, Yeong-Shin Park, Youngsik Seo, and Jong Myeong Lee (Samsung Electronics Co., Ltd., Korea)

**[WeE1-2] [Invited]** **09:30-10:00**

### Controlling Lateral Modification on Plasma Oxidation Using Optimizing Plasma Conditions during Isotropic Atomic Layer Etching

Ilyoung Kim, Taewan Kim, Seongkwang Lee, Hahnjoo Yoon, Sangman Park, and Yunsang Kim (SEMES, Korea)

**[WeE1-3]** **10:00-10:20**

### Plasma-Enhanced Atomic Layer Etching of Titanium Nitride Using Surface Fluorination or Chlorination

Heeju Ha, Hyeongwu Lee, Minsung Jeon, and Heeyeop Chae (Sungkyunkwan Univ., Korea)